

IN THE CLAIMS

Please amend Claim 1 shown in the following claim listing:

1. (Currently Amended) A quad flat non-leaded semiconductor package device comprising:
 - a discrete semiconductor die;
 - a die pad having a first lateral surface for supporting the semiconductor die; and
 - a plurality of vertical surfaces that are perpendicular to the first lateral surface, at least one bond pad having a first lateral surface and a plurality of vertical surfaces that are perpendicular to the first lateral surface;
 - at least one bond wire for connecting the discrete semiconductor die to the bond pad; and
 - an encapsulant for completely encapsulating the die, die pad, bond wire and bond pad having lateral and vertical outer surfaces, wherein the die pad is disposed at the perimeter of the encapsulant and partially exposed to one vertical outer surface of the encapsulant.
2. (Original) A quad flat non-leaded semiconductor package device according to claim 1, wherein a vertical surface of the die pad is provided with interlocking means.
3. (Original) A quad flat non-leaded semiconductor package device according to claim 1, wherein a vertical surface of the die pad is provided with means for interlocking the die pad vertically and laterally.
4. (Original) A quad flat non-leaded semiconductor package device according to claim 1, wherein a first and a second vertical surface of at least one pad is provided with interlocking means.
5. (Original) A quad flat non-leaded semiconductor package device according to claim 1, wherein a vertical surface of a bond pad is provided with interlocking means.